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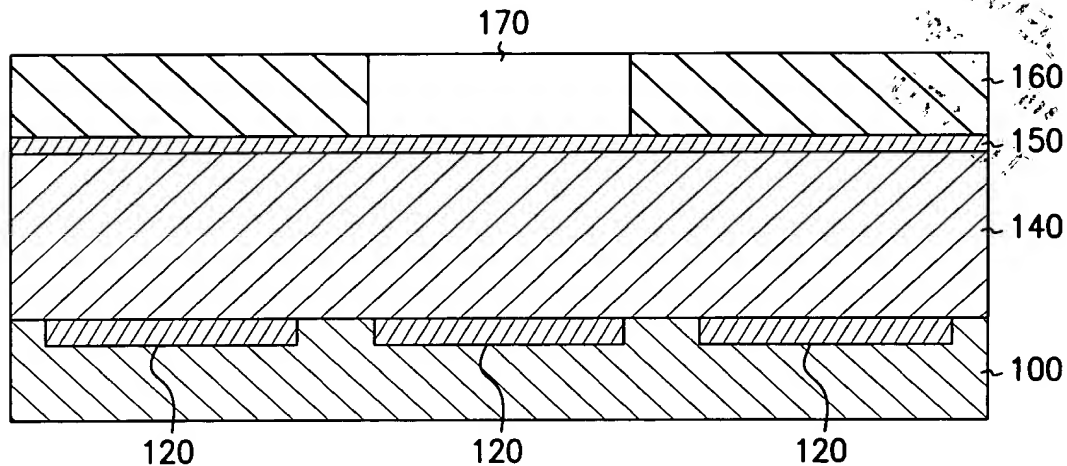


FIG. 1A (Prior Art)

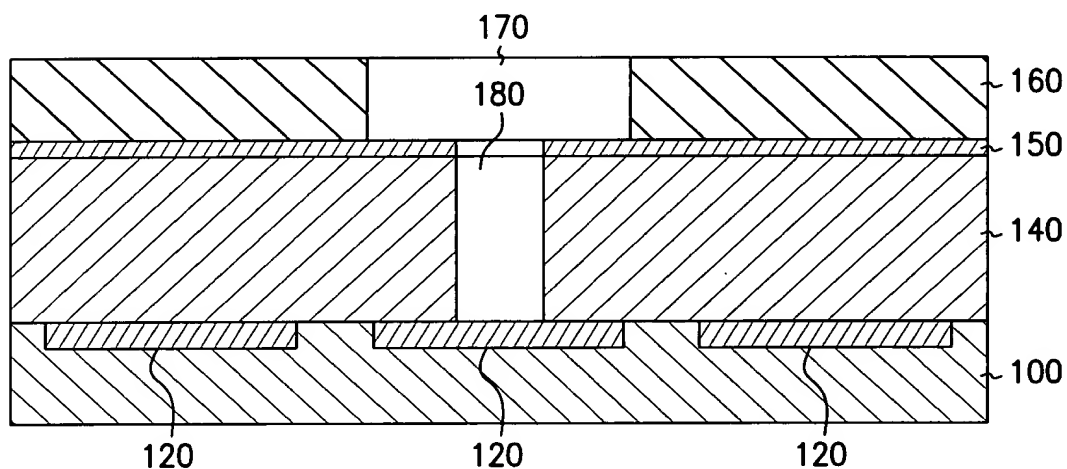


FIG. 1B (Prior Art)

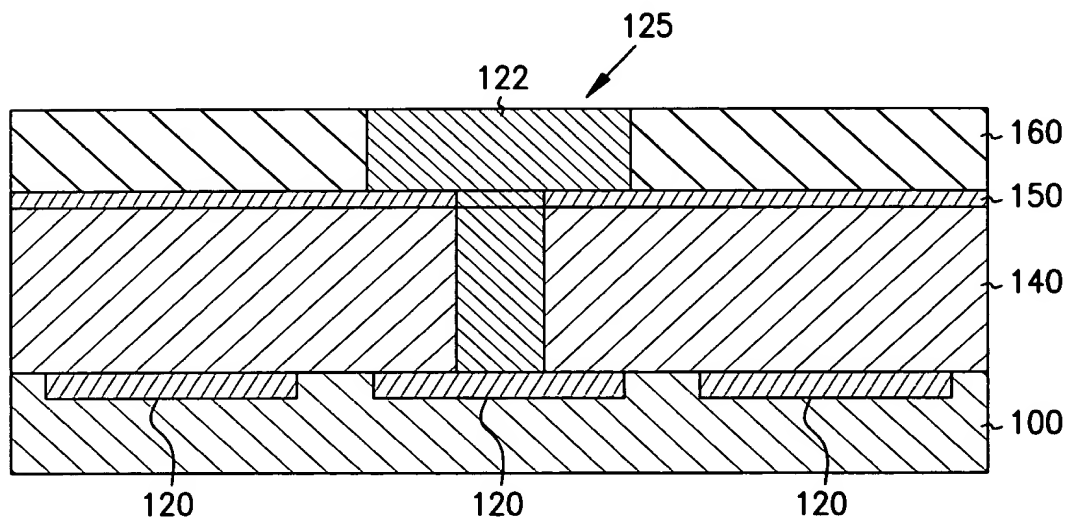


FIG. 1C (Prior Art)



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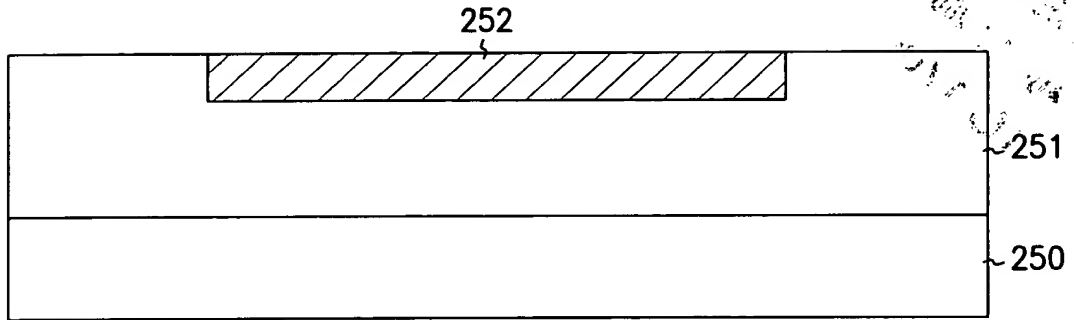


FIG. 2A

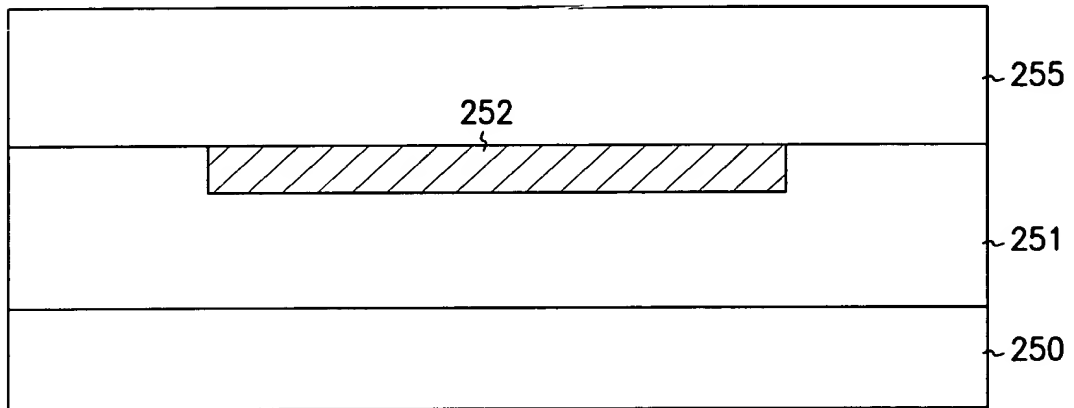


FIG. 2B

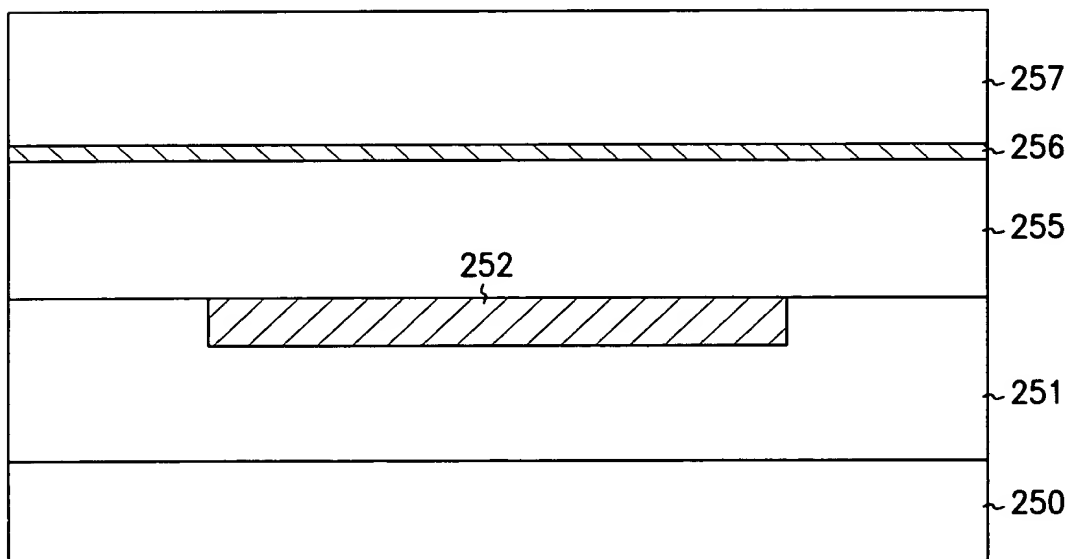


FIG. 2C



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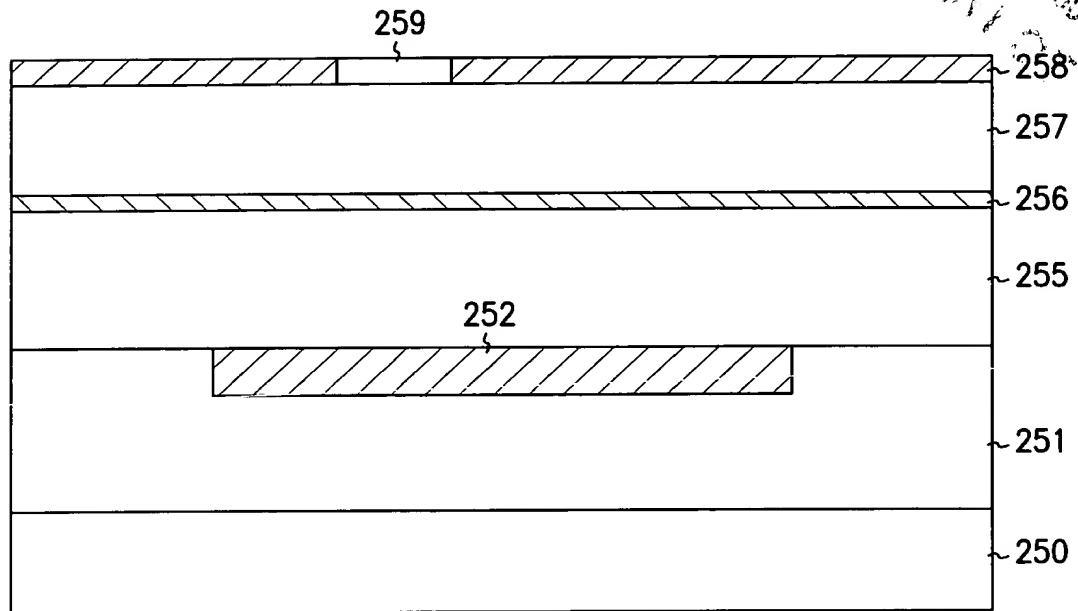


FIG. 2D

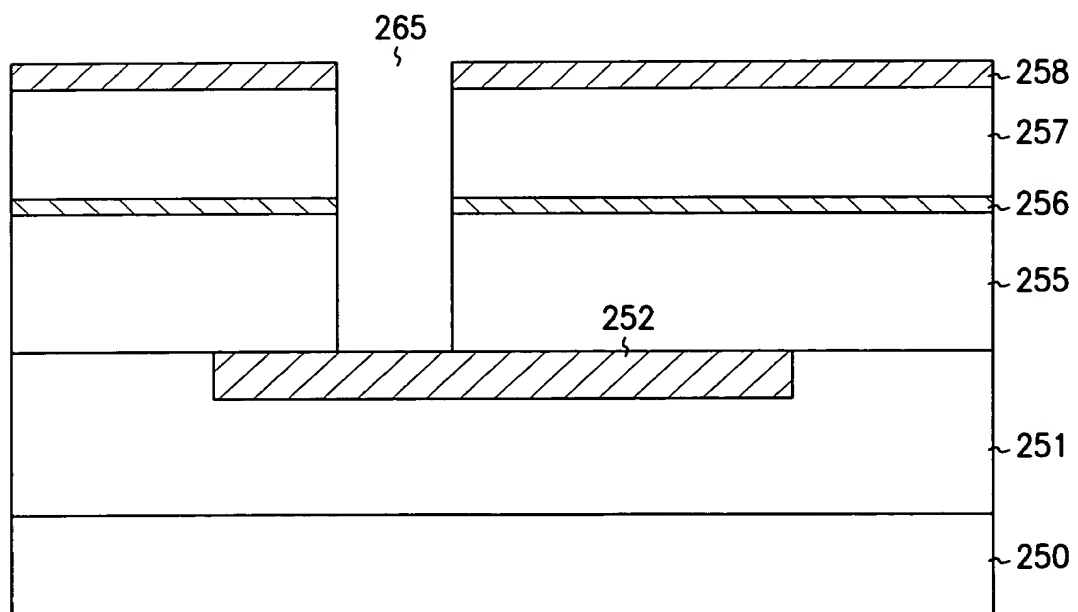


FIG. 2E

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TITLE: COPPER ELECTROLESS DEPOSITION TECHNOLOGY FOR ULSI METALIZATION
INVENTORS NAME: Kie Y. Ahn et al.
DOCKET NO.: 1303.016US1

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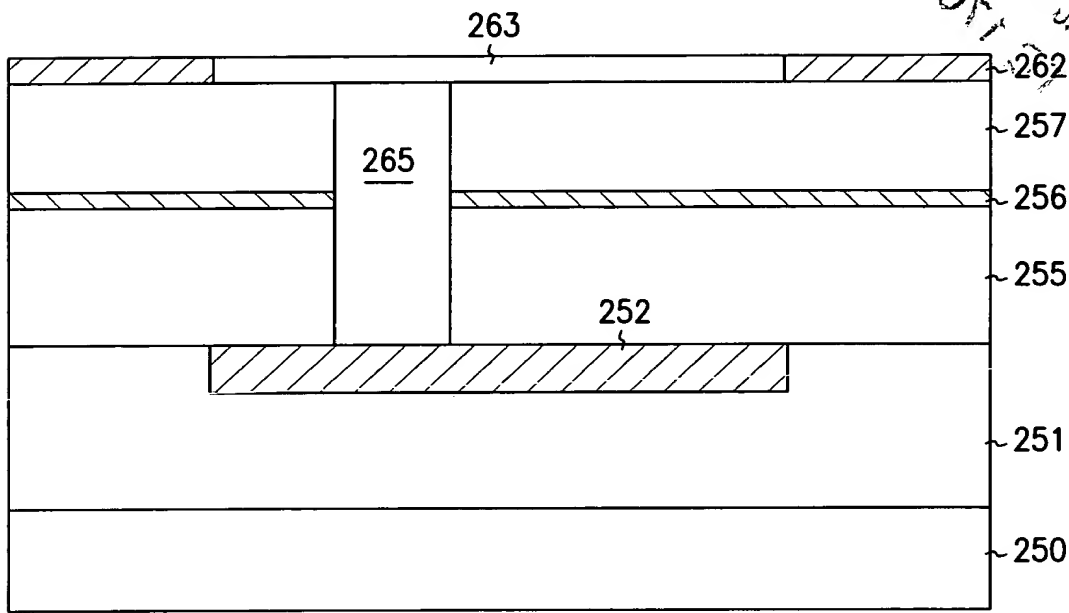


FIG. 2F

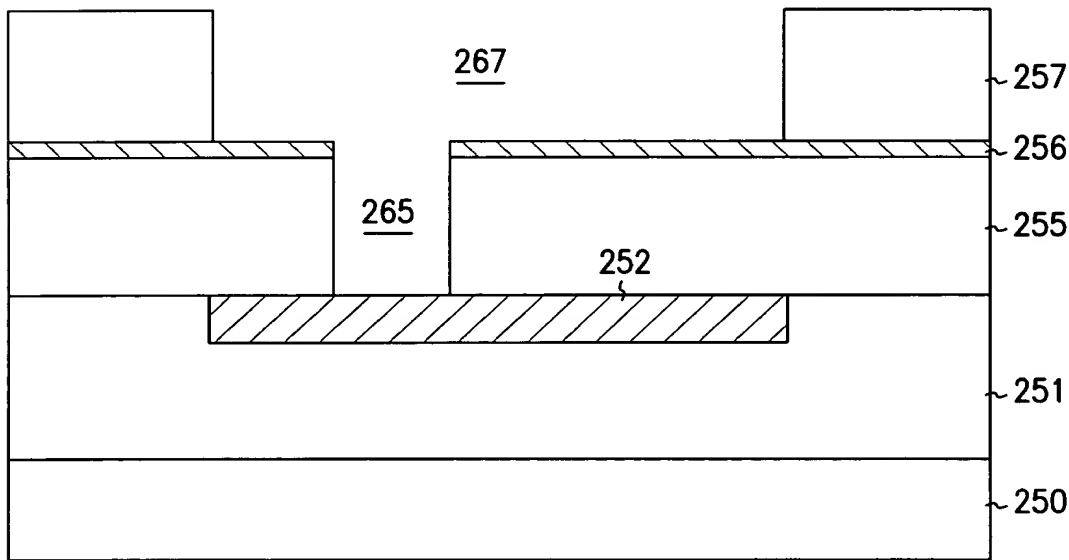


FIG. 2G



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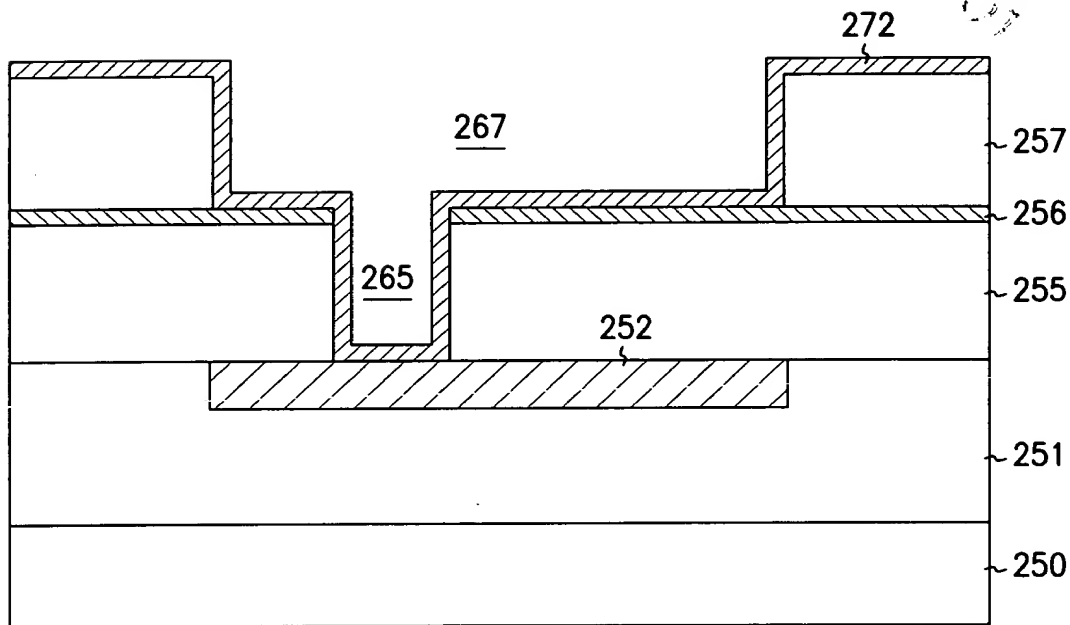


FIG. 2H

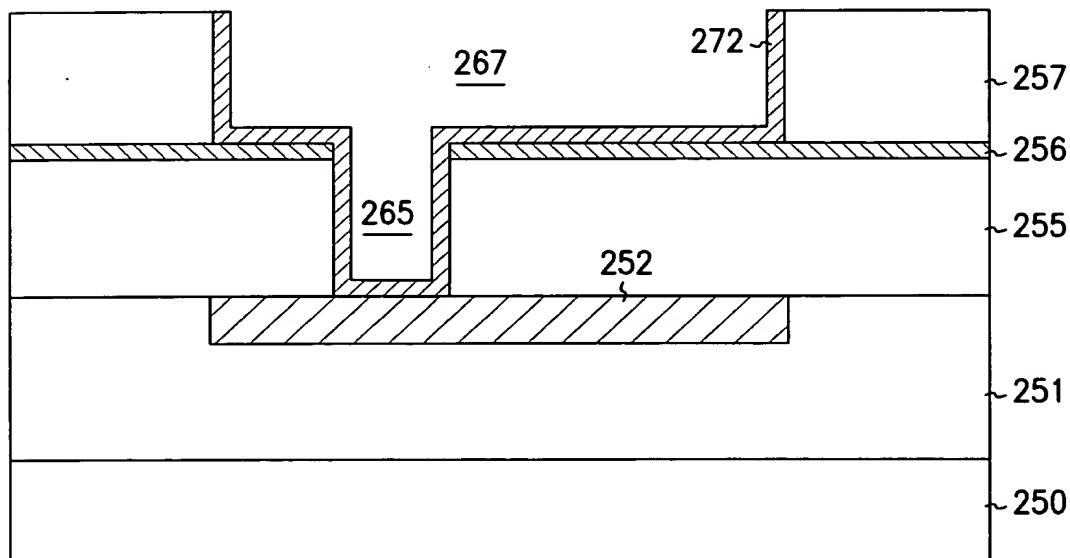


FIG. 2I



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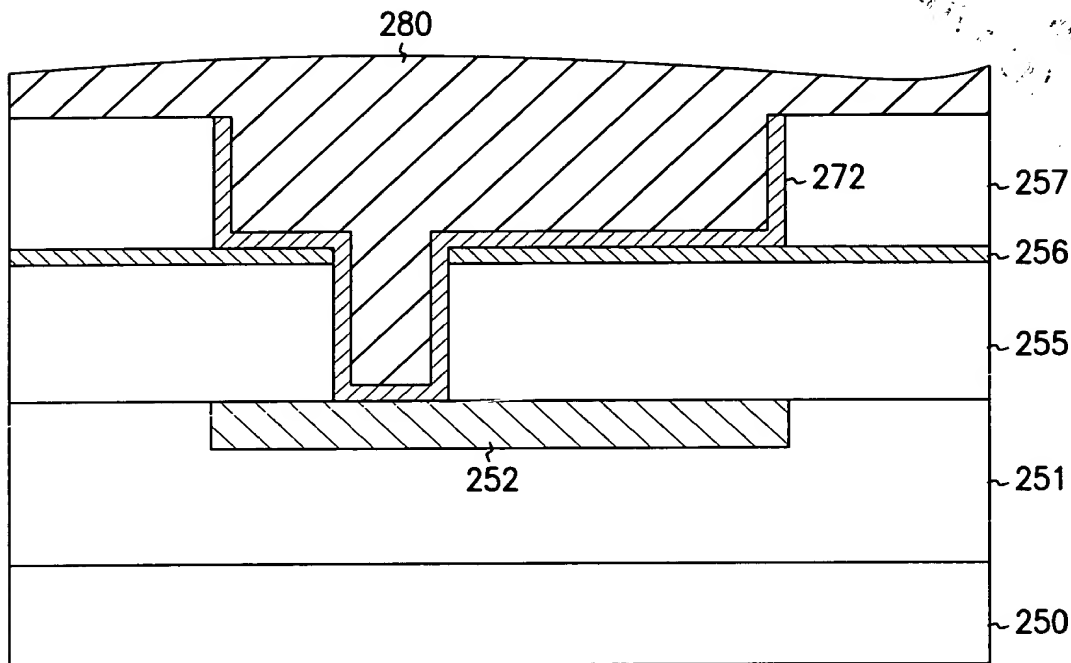


FIG. 2J

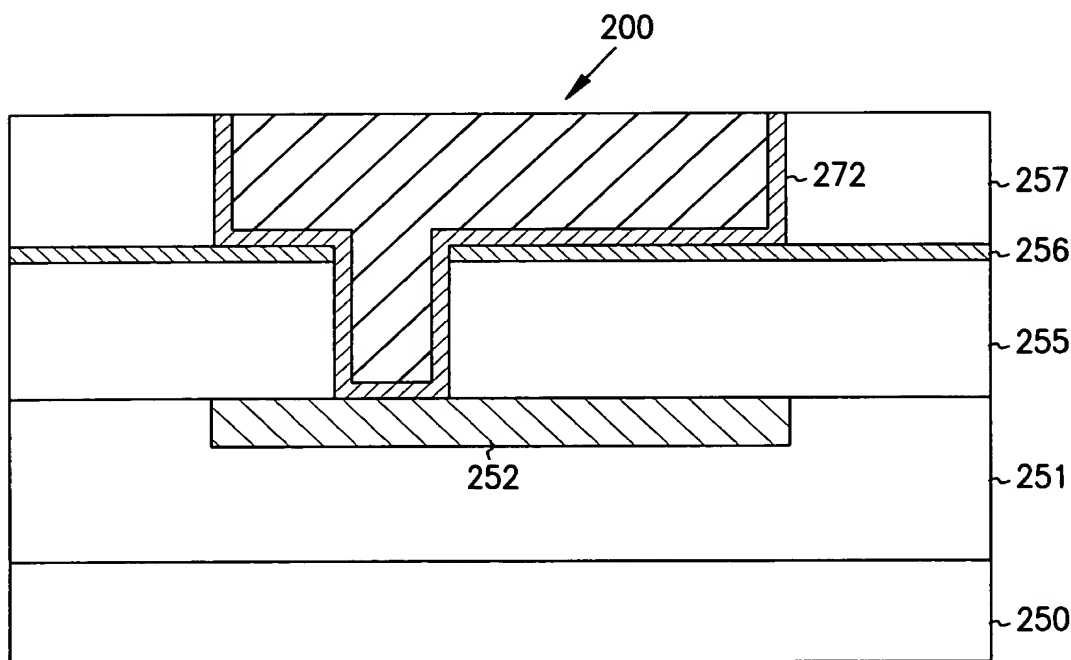


FIG. 2K



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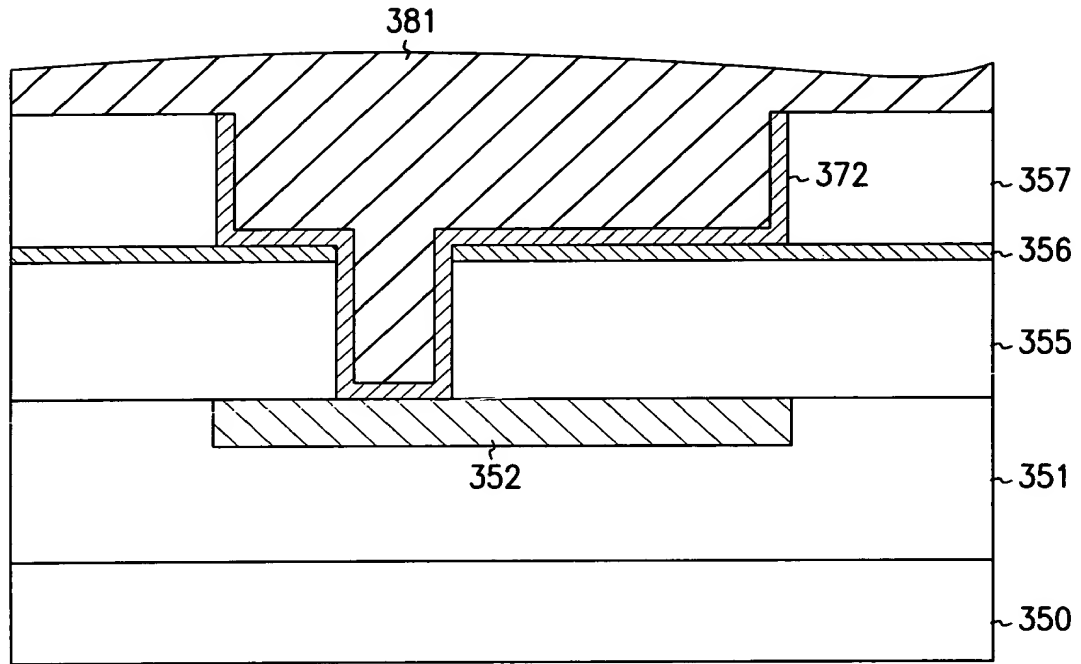


FIG. 3A

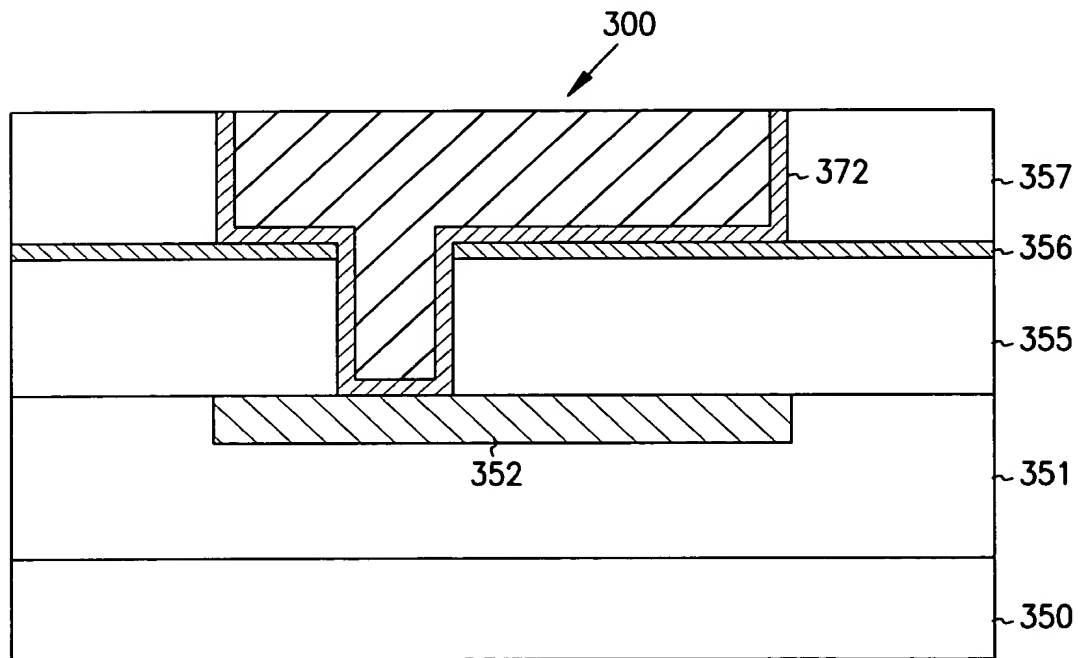


FIG. 3B

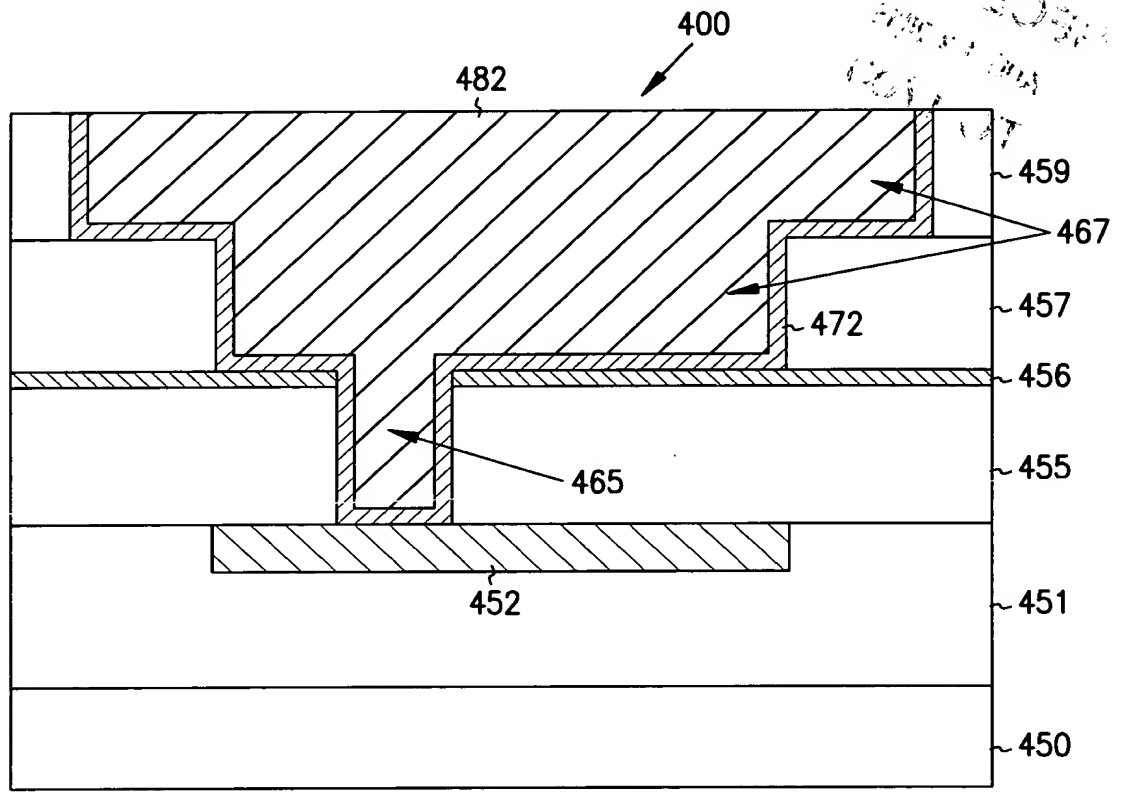


FIG. 4

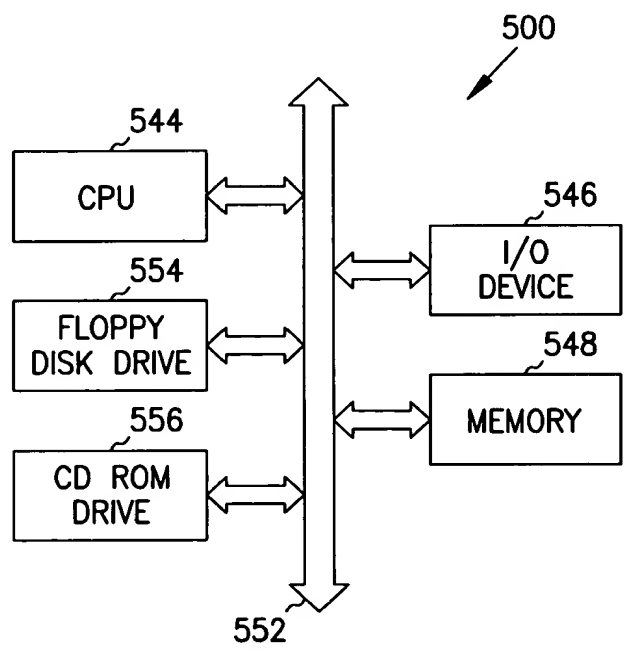


FIG. 5